

# Call for Papers

## **iMAPS New England – 43<sup>rd</sup> Symposium & Expo**

**The Largest Regional Symposium Dedicated to  
Microelectronics and Packaging**



The New England Chapter

## **May 3, 2016**

**Holiday Inn – Boxborough Conference Center  
Boxborough, Massachusetts**

- RF and Microwave – Innovations and Emerging Technologies
- 3D and Beyond
- High Reliability Interconnects
- SMT and Electronics Packaging
- Thermal Management
- Military and Defense Electronics
- Medical Device Packaging
- High Temp Electronics
- Automotive & Consumer Applications
- Near Hermetic Packaging
- MEMS Sensors and Nano Technology
- Printed Electronics
- Nanoelectronics and Optoelectronics Packaging
- Emerging Technologies

**Symposium Technical Chair  
Dmitry Marchenko, Microsemi  
Symposium Technical Co-Chair  
Dr. Parshant Kumar, Draper**

Please e-mail your 250 word abstract to:  
[dmitry.marchenko@live.com](mailto:dmitry.marchenko@live.com) or [pkumar@draper.com](mailto:pkumar@draper.com)

**Deadline for Submission – December 31, 2015**

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